FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16909

Generic Copy

Issue Date: 12-Sep-2012

TITLE: Final notification to qualify 3M UCT cold seal cover tape to replace 3M 2675 & Cheminix CHA200 heat seal cover tape for Wafer Scale Packaging (WSP) bare die products.

PROPOSED FIRST SHIP DATE: 12 Dec 2012

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Xavier Van Esch
< Xavier.VanEsch@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Xavier Van Esch
<Xavier.VanEsch@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

To qualify 3M UCT cold seal cover tape to replace 3M 2675 & Cheminix CHA200 heat seal cover tape for Wafer Scale Packaging (WSP) bare die products.

Purpose:
1) Eliminate bond pad contamination on 3M 2675 cover tape.
2) Eliminate die stick on Cheminix CHA200 cover tape

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Conditions	Results
MSL 1	85 degree C, 85% humidity	No bond pad contamination after 168hours No die stick on cover tape after 4 hours

ELECTRICAL CHARACTERISTIC SUMMARY:
No change.

CHANGED PART IDENTIFICATION:
There will be no changes to device identification. Normal assembly lot traceability codes will identify the changed devices by date code.

List of affected Customer Specific Parts:

SZC498D27CATR
TC10016TR
0HSBA-003-XDS
0HSBA-004-XDS
0HSBA-006-XDS
0MAFA-002-XDS
0SCIA-005-XDS
0SHIA-009-XDS
0SHIA-010-XDS